

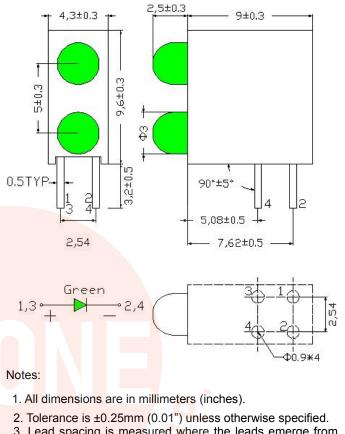
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	LASTURACI
	Features:
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- 1. Chip material: Gap
- 2. Emitted color : Green
- 3. Lens Appearance : Green Diffused
- 4. Designed for ease in circuit board assembly.
- 5. Black case enhance contrast ratio.
- 6. Solid state light source.
- 7. Reliable and rugged.
- 8. This product don't contained restriction substance, compliance RoHS standard.

Applications:

- 1. TV set
- 2. Monitor
- 3. Telephone
- 4. Computer
- 5. Circuit board

Package dimensions



- 3. Lead spacing is measured where the leads emerge from the package.
- 4. Specifications are subject to change without notice.

● Absolute Maximum Ratings(Ta=25°C)

Parameter	Symbol	Green	Unit	
Power Dissipation	Pd	75	mW	
Forward Current	lF	30	mA	
Peak Forward Current*1	I _{FP}	50	mA	
Reverse Voltage	V _R	5	V	
Operating Temperature	Topr	-30 ℃ ~80 ℃		
Storage Temperature	Tstg	-40℃~85℃		
Soldering Temperature	Tsol	260℃max (for 5 seconds)		
Hand Soldering Temperature	Tsol	$350^\circ C \max(\text{for } 3 \text{ seconds })$		

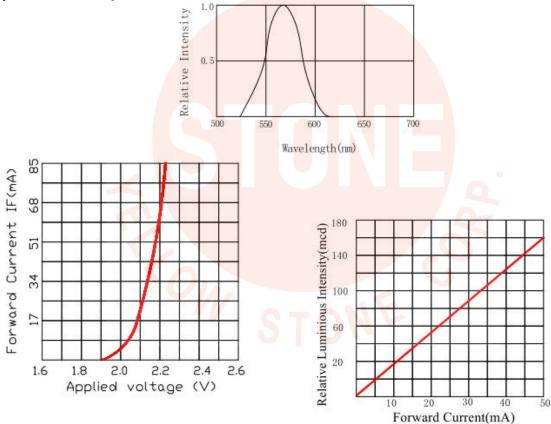
 *1 Condition for I_{FP} is pulse of 1/10 duty and 0.1msec width.

stone 早安股份有限公司 YELLOW STONE CORP.

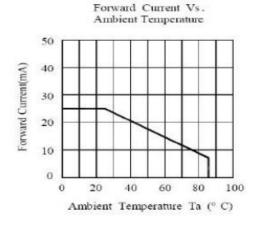
● Electrical and optical characteristics(Ta=25[°]C)

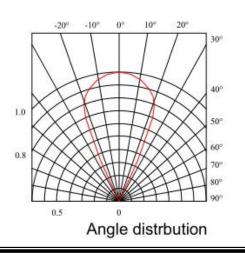
Parameter	Symbol	Condition	Color	Min.	Тур.	Max.	Unit
Forward Voltage	VF	I _F =20mA	Green	1.8	2.2	2.6	V
Luminous Intensity	lv	I _F =20mA	Green	40	50	80	mcd
Reverse Current	I _R	V _R =5V	Green	-	-	10	μA
Peak Wave Length	λρ	I _F =20mA	Green	-	-	-	nm
Dominant Wave Length	λ d	I _F =20mA	Green	565	570	575	nm
Spectral Line Half-width	Δλ	I _F =20mA	Green	-	_	-	nm
Viewing Angle	2 θ _{1/2}	I _F =20mA	Green	-	50	-	deg

Typical electro-optical characteristics curves



Forward Currend Vs Relative luminious Intensity



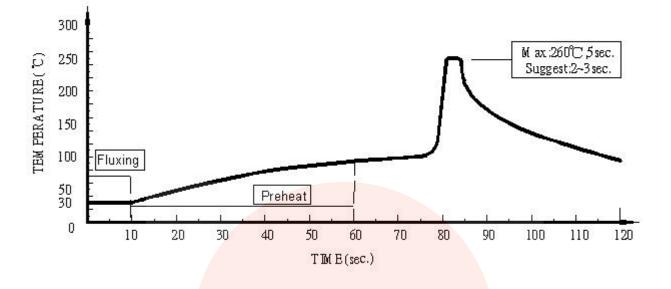




DIP Soldering



BL-30GG-2



- 1. Please avoid any external stress applied to the lead-frames and epoxy while the LEDs are at high temperature, especially during soldering
- 2. DIP soldering and hand soldering should not be done more than one time.
- 3. After soldering, avoid the epoxy lens from mechanical shock or vibration until the LEDs are back to room temerature.
- 4. Avoid rapid cooling during temperature ramp-down process
- 5. Although the soldering condition is recommended above, soldering at the lowest possible temperature is feasible for the LEDs

●IRON Soldering

A: Max: 350°C Within 3 sec. One time only.

B: The products of 3mm without flange, welding condition of flat plate PCB Max: 350 $^\circ\!C$ Within 2 sec. One time only

